

# FAN7390A

## High-Current, High & Low-Side, Gate-Drive IC

### Features

- Floating Channels for Bootstrap Operation to +600 V
- Typically 4.5 A / 4.5 A Sourcing / Sinking Current Driving Capability
- Common-Mode dv/dt Noise-Canceling Circuit
- Built-in Under-Voltage Lockout for Both Channels
- Matched Propagation Delay for Both Channels
- Logic ( $V_{SS}$ ) and Power (COM) Ground  $\pm 5V$  Offset
- 3.3 V and 5 V Input Logic Compatible
- Output In-phase with Input

### Applications

- Plasma Display Panel (PDP) Sustain Driver
- High Intensity Discharge (HID) Lamp Ballast
- SMPS
- Motor Driver

### Description

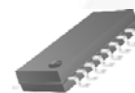
The FAN7390A is a monolithic high- and low-side gate-drive IC, which can drive high-speed MOSFETs and IGBTs that operate up to +600 V. It has a buffered output stage with all NMOS transistors designed for high pulse current driving capability and minimum cross-conduction.

Fairchild's high-voltage process and common-mode noise canceling techniques provide stable operation of the high-side driver under high-dv/dt noise circumstances. An advanced level-shift circuit offers high-side gate driver operation up to  $V_S = -9.8 V$  (typical) for  $V_{BS} = 15 V$ .

The UVLO circuit prevents malfunction when  $V_{DD}$  and  $V_{BS}$  are lower than the specified threshold voltage.

The high-current and low-output voltage-drop feature make this device suitable for the PDP sustain pulse driver, motor driver, switching power supply, and high-power DC-DC converter applications.

14-SOP



### Ordering Information

Part Number	Package	Operating Temperature Range	Packing Method
FAN7390AMX1	14-SOP	-40°C ~ 125°C	Tape & Reel



### Typical Application Circuit

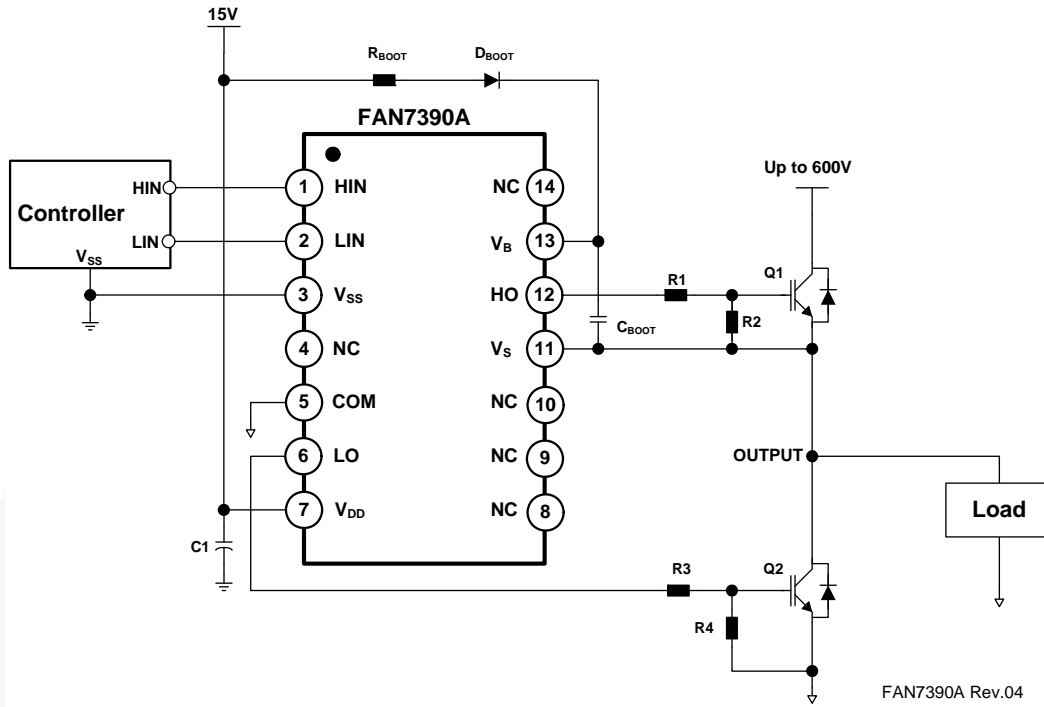


Figure 1. Application Circuit for Half-Bridge (Referenced 14-SOP)

### Internal Block Diagram

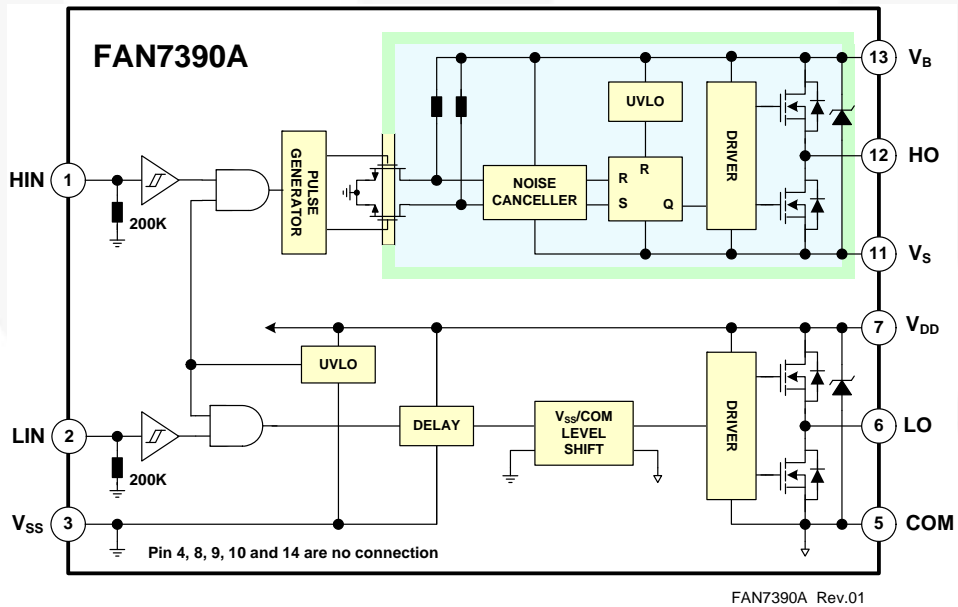


Figure 2. Functional Block Diagram (Referenced 14-SOP)

## Pin Configurations

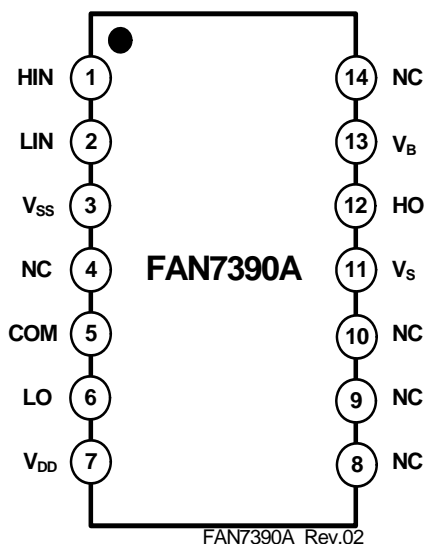


Figure 3. Pin Assignments (Top View)

## Pin Definitions

14-Pin	Name	Description
1	HIN	Logic Input for High-Side Gate Driver Output
2	LIN	Logic Input for Low-Side Gate Driver Output
3	V <sub>SS</sub>	Logic Ground
5	COM	Low-Side Driver Return
6	LO	Low-Side Driver Output
7	V <sub>DD</sub>	Low-Side and Logic Part Supply Voltage
11	V <sub>S</sub>	High-Voltage Floating Supply Return
12	HO	High-Side Driver Output
13	V <sub>B</sub>	High-Side Floating Supply
4, 8, 9, 10, 14	NC	No Connect

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A=25^{\circ}\text{C}$ , unless otherwise specified.

Symbol	Characteristics	Min.	Max.	Unit
$V_S$	High-Side Floating Supply Offset Voltage	$V_B - V_{SHUNT}$	$V_B + 0.3$	V
$V_B$	High-Side Floating Supply Voltage	-0.3	625.0	V
$V_{HO}$	High-Side Floating Output Voltage, HO Pin	$V_S - 0.3$	$V_B + 0.3$	V
$V_{DD}$	Low-Side and Logic Fixed Supply Voltage	-0.3	$V_{SHUNT}$	V
$V_{LO}$	Low-Side Output Voltage, LO Pin	-0.3	$V_{DD} + 0.3$	V
$V_{IN}$	Logic Input Voltage (HIN and LIN)	$V_{SS} - 0.3$	$V_{DD} + 0.3$	V
$V_{SS}$	Logic Ground	$V_{DD} - 25$	$V_{DD} + 0.3$	V
$dV_S/dt$	Allowable Offset Voltage Slew Rate		50	V/ns
$P_D^{(1)(2)(3)}$	Power Dissipation		1.0	W
$\theta_{JA}$	Thermal Resistance, Junction-to-Ambient		110	$^{\circ}\text{C}/\text{W}$
$T_J$	Junction Temperature		+150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature		+150	$^{\circ}\text{C}$

### Notes:

- Mounted on 76.2 x 114.3 x 1.6 mm PCB (FR-4 glass epoxy material).
- Refer to the following standards:
  - JESD51-2: Integral circuits thermal test method environmental conditions - natural convection; and
  - JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages.
- Do not exceed  $P_D$  maximum under any circumstances.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
$V_B$	High-Side Floating Supply Voltage	$V_S + 10$	$V_S + 20$	V
$V_S$	High-Side Floating Supply Offset Voltage	$6 - V_{DD}$	600	V
$V_{HO}$	High-Side Output Voltage	$V_S$	$V_B$	V
$V_{DD}$	Low-Side and Logic Supply Voltage	10	20	V
$V_{LO}$	Low-Side Output Voltage	COM	$V_{DD}$	V
$V_{IN}$	Logic Input Voltage (HIN and LIN)	$V_{SS}$	$V_{DD}$	V
$T_A$	Operating Ambient Temperature	-40	+125	$^{\circ}\text{C}$

## Electrical Characteristics

$V_{BIAS}$  ( $V_{DD}$ ,  $V_{BS}$ )=15.0 V,  $V_S=V_{SS}=COM$ ,  $T_A=25^\circ C$ , unless otherwise specified. The  $V_{IL}$ ,  $V_{IH}$ , and  $I_{IN}$  parameters are referenced to  $V_{SS}/COM$  and are applicable to the respective input signals HIN and LIN. The  $V_O$  and  $I_O$  parameters are referenced to COM and  $V_S$  is applicable to the respective output signals HO and LO.

Symbol	Characteristics	Condition	Min.	Typ.	Max.	Unit
<b>POWER SUPPLY SECTION (<math>V_{DD}</math> AND <math>V_{BS}</math>)</b>						
$V_{DDUV+}$ $V_{BSUV+}$	$V_{DD}$ and $V_{BS}$ Supply Under-Voltage Positive-Going Threshold		8.0	8.8	9.8	V
$V_{DDUV-}$ $V_{BSUV-}$	$V_{DD}$ and $V_{BS}$ Supply Under-Voltage Negative-Going Threshold		7.4	8.3	9.0	
$V_{DDUVH}$ $V_{BSUVH}$	$V_{DD}$ and $V_{BS}$ Supply Under-Voltage Lockout Hysteresis Voltage			0.5		
$I_{LK}$	Offset Supply Leakage Current	$V_B=V_S=600$ V			50	$\mu A$
$I_{QBS}$	Quiescent $V_{BS}$ Supply Current	$V_{IN}=0$ V or 5 V		45	80	
$I_{QDD}$	Quiescent $V_{DD}$ Supply Current	$V_{IN}=0$ V or 5 V		75	110	
$I_{PBS}$	Operating $V_{BS}$ Supply Current	$f_{IN}=20$ kHz, rms value		530	640	$\mu A$
$I_{PDD}$	Operating $V_{DD}$ Supply Current	$f_{IN}=20$ kHz, rms value		530	640	
<b>SHUNT REGULATOR SECTION</b>						
$V_{SHUNT}$	$V_{DD}$ and $V_{BS}$ Shunt Regulator Clamping Voltage	$V_{DD}=\text{Sweep}$ or $V_{BS}=\text{Sweep}$ , $I_{SHUNT}=5$ mA	21	23	25	V
<b>LOGIC INPUT SECTION (HIN, LIN)</b>						
$V_{IH}$	Logic "1" Input Voltage		2.5			V
$V_{IL}$	Logic "0" Input Voltage				1.2	
$I_{IN+}$	Logic "1" Input Bias Current	$V_{IN}=5$ V		25	50	$\mu A$
$I_{IN-}$	Logic "0" Input Bias Current	$V_{IN}=0$ V		1.0	2.0	
$R_{IN}$	Input Pull-down Resistance		100	200		K $\Omega$
<b>GATE DRIVER OUTPUT SECTION (HO, LO)</b>						
$V_{OH}$	High-Level Output Voltage, $V_{BIAS}-V_O$	No Load			1.0	V
$V_{OL}$	Low-Level Output Voltage, $V_O$	No Load			35	mV
$I_{O+}$	Output High, Short-Circuit Pulsed Current <sup>(4)</sup>	$V_O=0$ V, $V_{IN}=5$ V, $PW<10$ $\mu s$	3.5	4.5		A
$I_{O-}$	Output Low, Short-Circuit Pulsed Current <sup>(4)</sup>	$V_O=15$ V, $V_{IN}=0$ V, $PW<10$ $\mu s$	3.5	4.5		
$V_S$	Allowable Negative $V_S$ Pin Voltage for HIN Signal Propagation to HO			-9.8	-7.0	V
$V_{SS-COM}$	$V_{SS}-COM/COM-V_{SS}$ Voltage Endurability		-5		5	V

### Note:

4. This parameter guaranteed by design.

## Dynamic Electrical Characteristics

$V_{BIAS}$  ( $V_{DD}$ ,  $V_{BS}$ )=15.0 V,  $V_S=V_{SS}=COM=0$  V,  $C_L=1000$  pF and  $T_A=25^\circ C$  unless otherwise specified.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
$t_{on}$	Turn-On Propagation Delay	$V_S=0$ V		140	200	ns
$t_{off}$	Turn-Off Propagation Delay	$V_S=0$ V		140	200	
MT	Delay Matching, HS & LS Turn-On/Off			15	50	
$t_r$	Turn-on Rise Time			25	50	
$t_f$	Turn-off Fall Time			20	45	

## Typical Characteristics

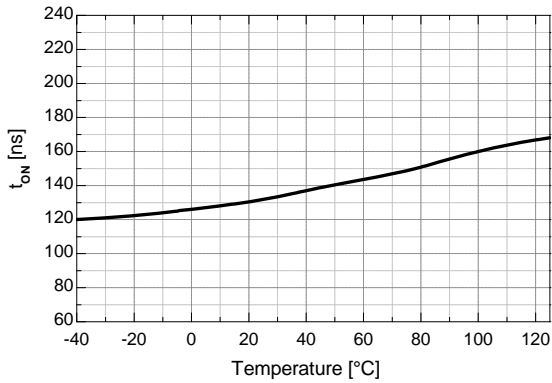


Figure 4. Turn-On Propagation Delay vs. Temperature

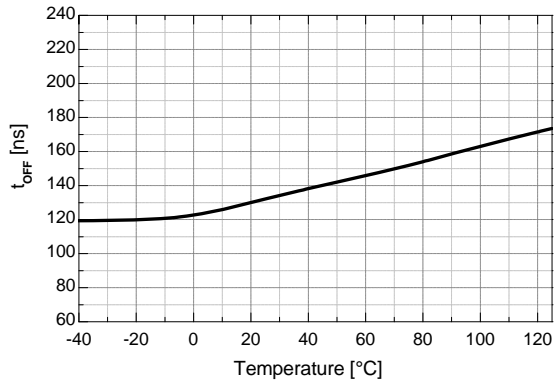


Figure 5. Turn-Off Propagation Delay vs. Temperature

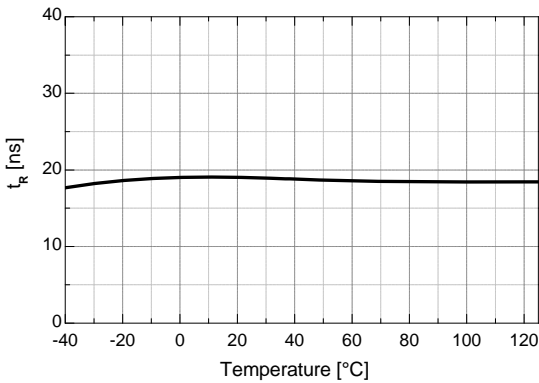


Figure 6. Turn-On Rise Time vs. Temperature

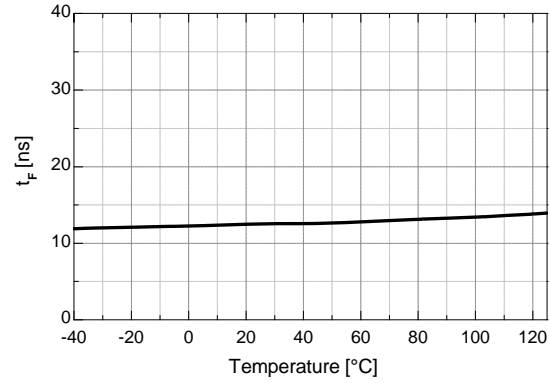


Figure 7. Turn-Off Fall Time vs. Temperature

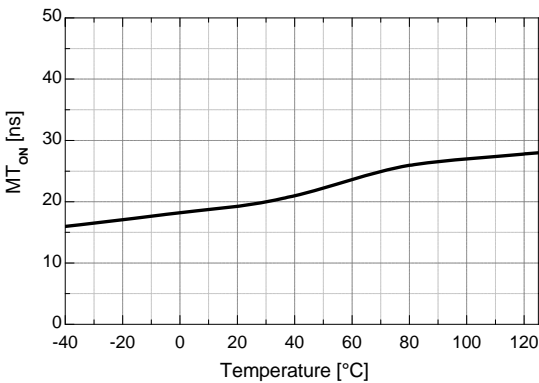


Figure 8. Turn-On Delay Matching vs. Temperature

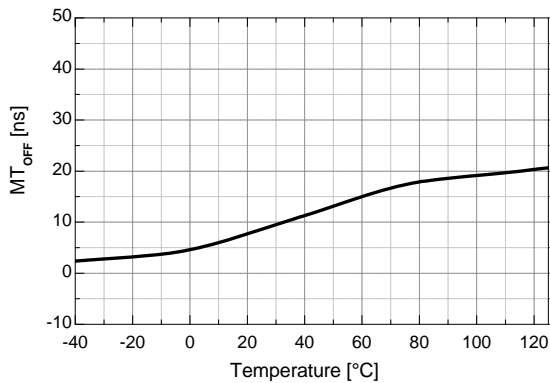


Figure 9. Turn-Off Delay Matching vs. Temperature

Typical Characteristics (Continued)

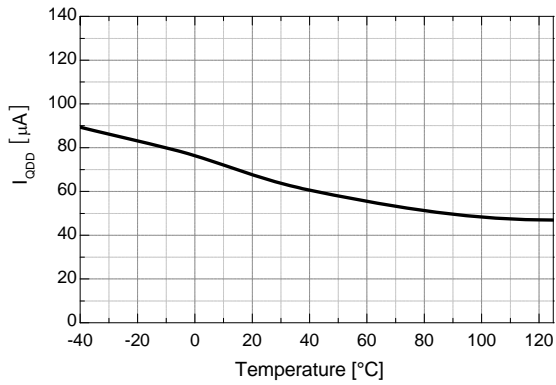


Figure 10. Quiescent  $V_{DD}$  Supply Current vs. Temperature

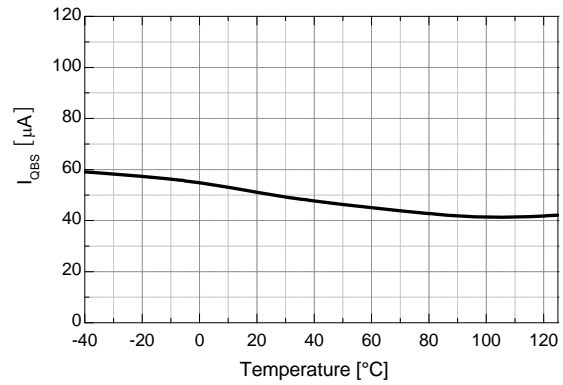


Figure 11. Quiescent  $V_{BS}$  Supply Current vs. Temperature

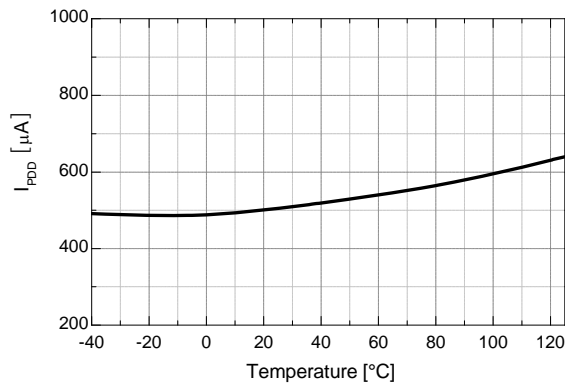


Figure 12. Operating  $V_{DD}$  Supply Current vs. Temperature

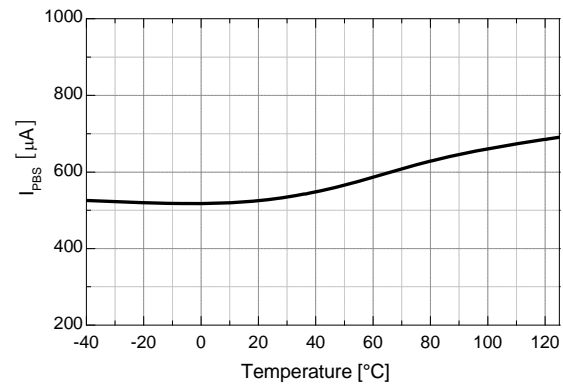


Figure 13. Operating  $V_{BS}$  Supply Current vs. Temperature

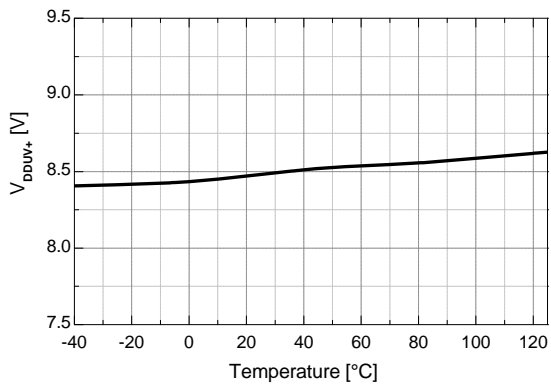


Figure 14.  $V_{DD}$  UVLO+ vs. Temperature

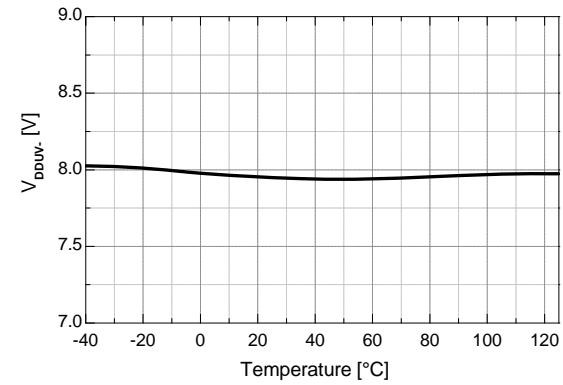


Figure 15.  $V_{DD}$  UVLO- vs. Temperature

Typical Characteristics (Continued)

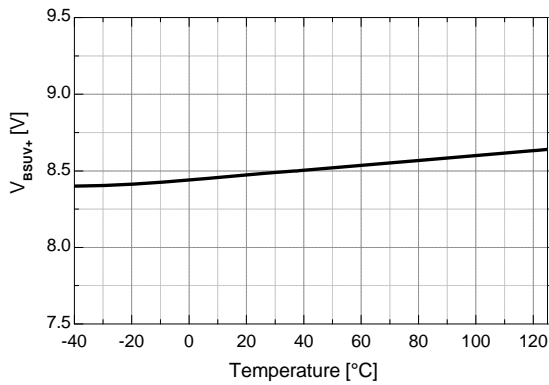


Figure 16. V<sub>BS</sub> UVLO+ vs. Temperature

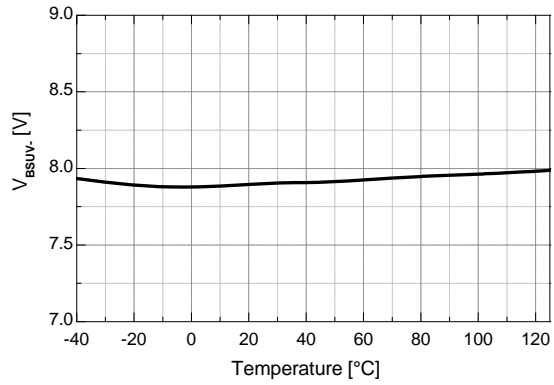


Figure 17. V<sub>BS</sub> UVLO- vs. Temperature

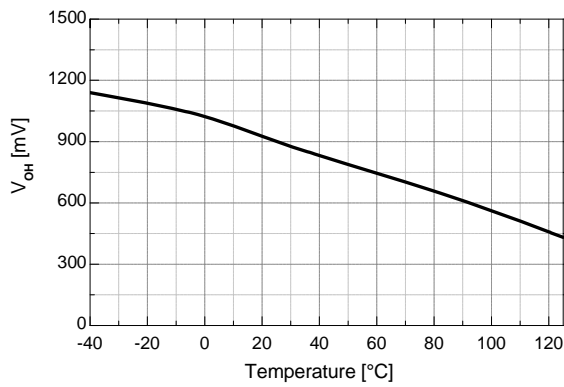


Figure 18. High-Level Output Voltage vs. Temperature

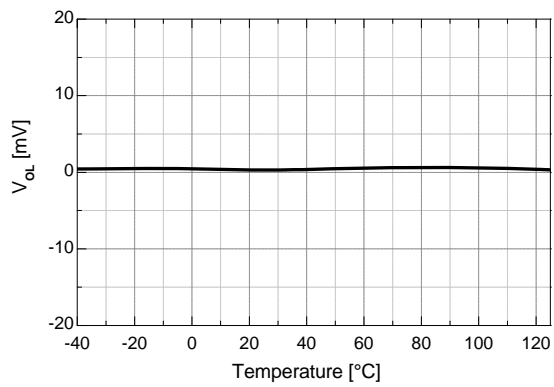


Figure 19. Low-Level Output Voltage vs. Temperature

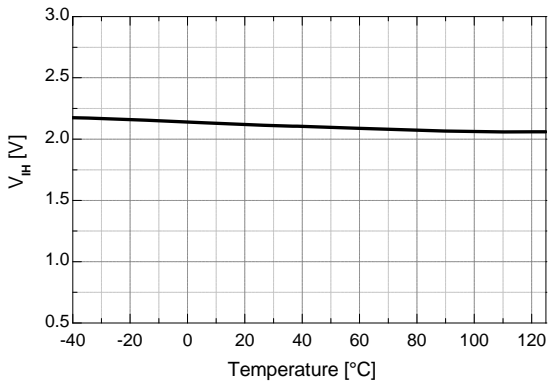


Figure 20. Logic HIGH Input Voltage vs. Temperature

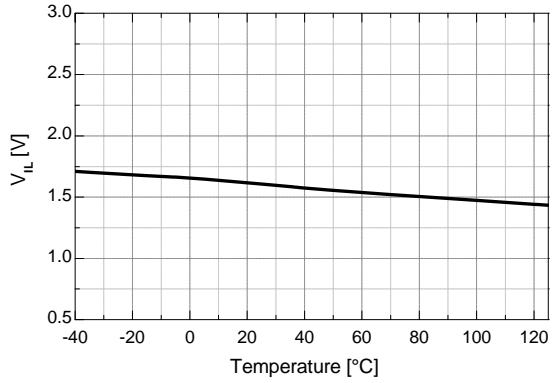


Figure 21. Logic LOW Input Voltage vs. Temperature



Typical Characteristics (Continued)

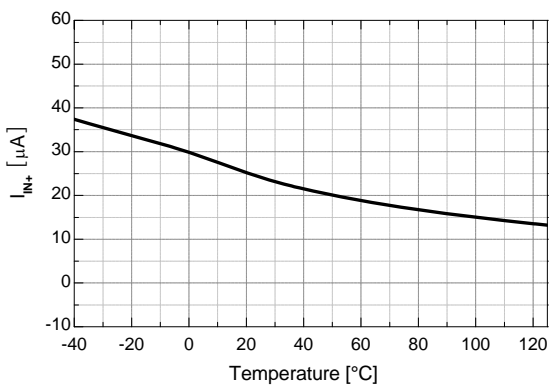


Figure 22. Logic Input High Bias Current vs. Temperature

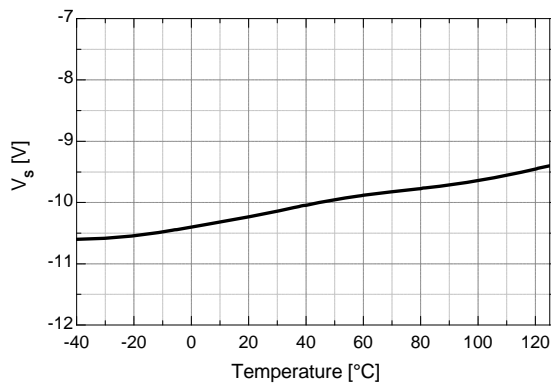


Figure 23. Allowable Negative  $V_S$  Voltage vs. Temperature



## Switching Time Definitions

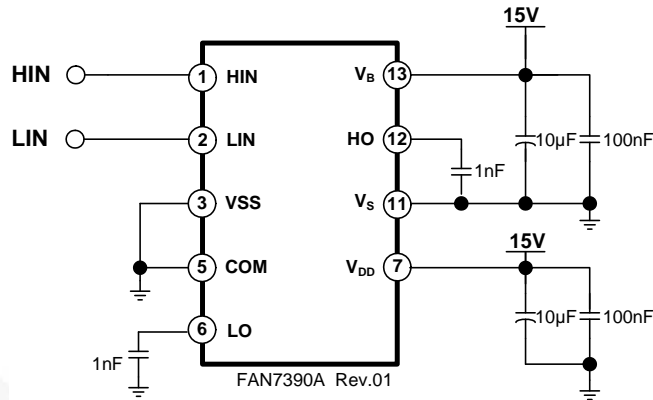


Figure 24. Switching Time Test Circuit (Referenced 8-SOP)

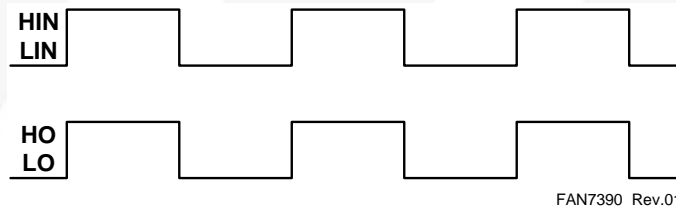


Figure 25. Input / Output Timing Diagram

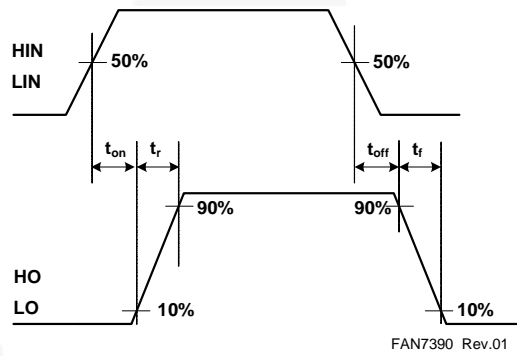


Figure 26. Switching Time Waveform Definitions

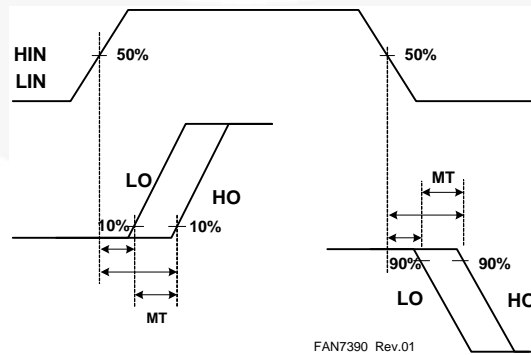
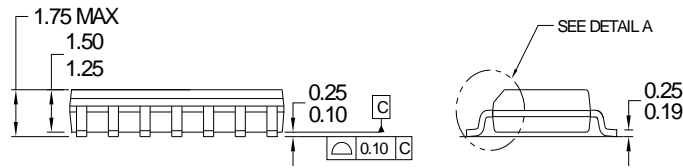
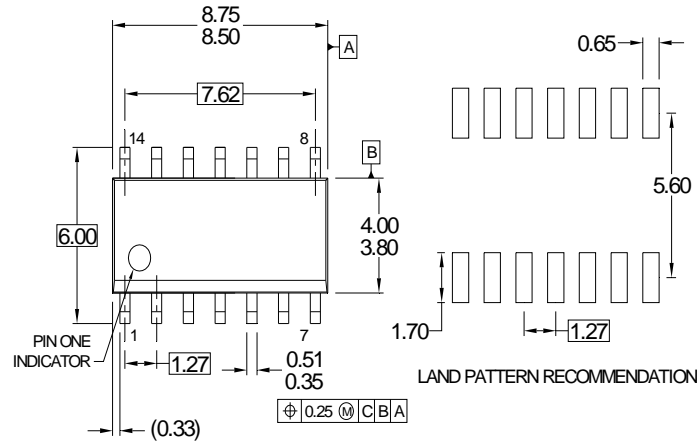
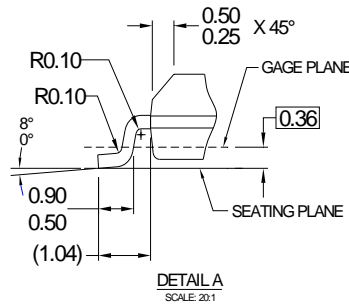


Figure 27. Delay Matching Waveform Definitions

Package Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED



- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

Figure 28. 14-Lead, Small Outline Package (SOP)

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| AccuPower™   | FRFET®   | PowerXS™   | the power franchise   |
| AX-CAP™*   | Global Power Resource™                         | Programmable Active Droop™   | TinyBoost™  |
| BitSiC™  | GreenBridge™                                   | QFET®  | TinyBuck™   |
| Build it Now™  | Green FPS™                                     | QS™  | TinyCalc™   |
| CorePLUS™  | Green FPS™ e-Series™                           | Quiet Series™  | TinyLogic®  |
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| CROSS VOLT™  | GTO™   |  ™                | TinyPower™  |
| CTL™   | IntelliMAX™                                    | Saving our world, 1mW/W/kW at a time™  | TinyPWM™  |
| Current Transfer Logic™  | ISOPLANAR™                                     | SignalWise™  | TinyWire™   |
| DEUXPEED®  | Making Small Speakers Sound Louder and Better™ | SmartMax™  | TranSiC™  |
| Dual Cool™   | MegaBuck™                                      | SMART START™   | TriFault Detect™  |
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|  Fairchild® | MicroPak2™                                     | SuperFET®  | UHC®  |
| Fairchild Semiconductor®   | MillerDrive™                                   | SuperSOT™-3  | Ultra FRFET™  |
| FACT Quiet Series™   | MotionMax™                                     | SuperSOT™-6  | UniFET™   |
| FACT®  | mWSaver™                                       | SuperSOT™-8  | VCS™  |
| FAST®  | OptoHi™  | SupreMOS®  | VisualMax™  |
| FastvCore™   | OPTOLOGIC®                                     | SyncFET™   | VoltagePlus™  |
| FETBench™  | OPTOPLANAR®                                    | Sync-Lock™   | XS™   |
| FlashWriter®*  |  |  SYSTEM GENERAL®* |   |
| FPS™   |  |  |   |

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2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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